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FIG. 1

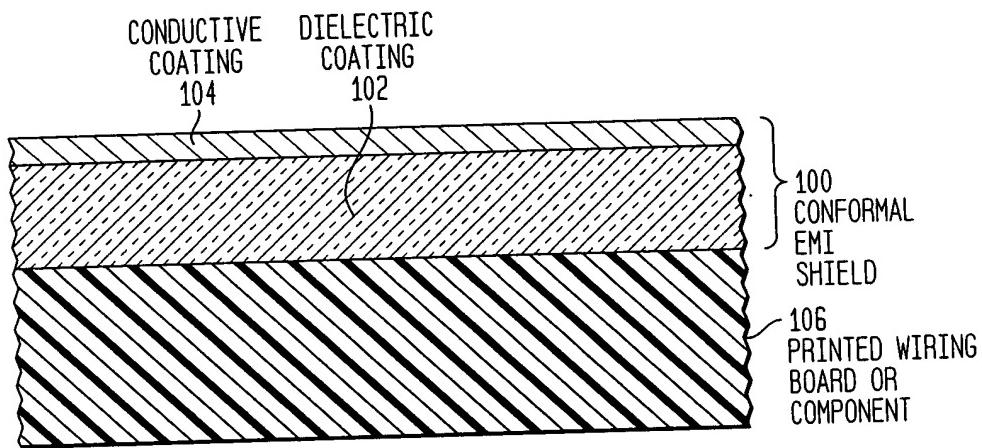
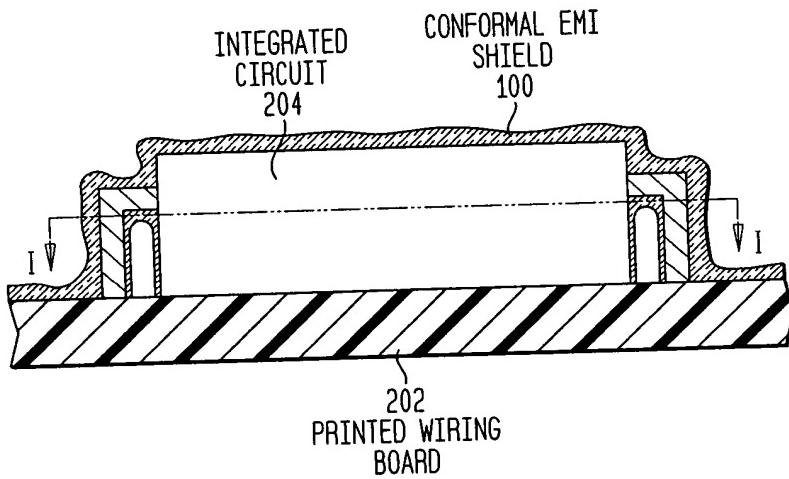
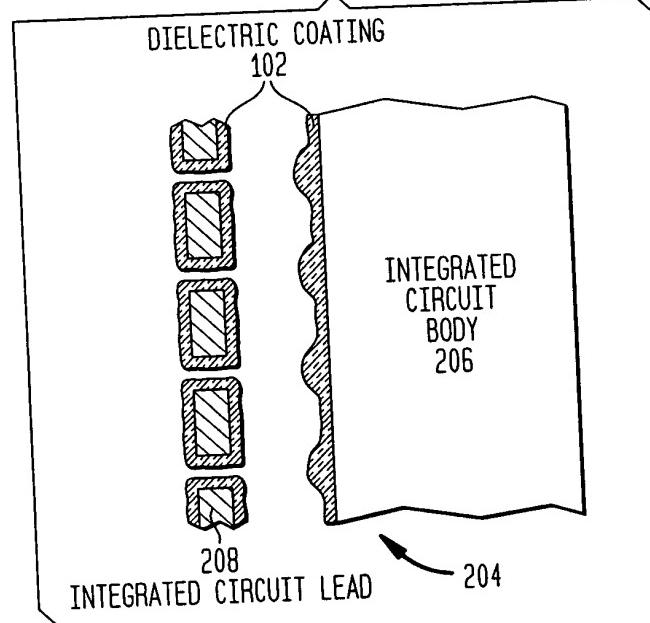


FIG. 2A



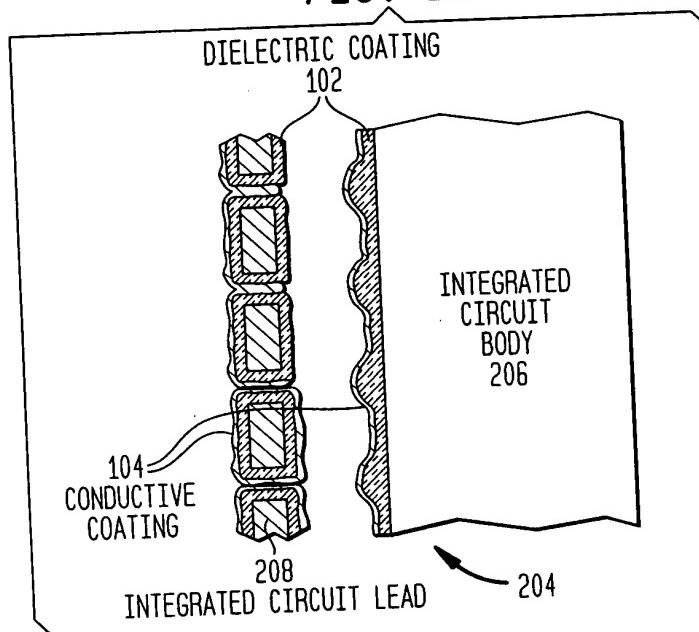
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FIG. 2B



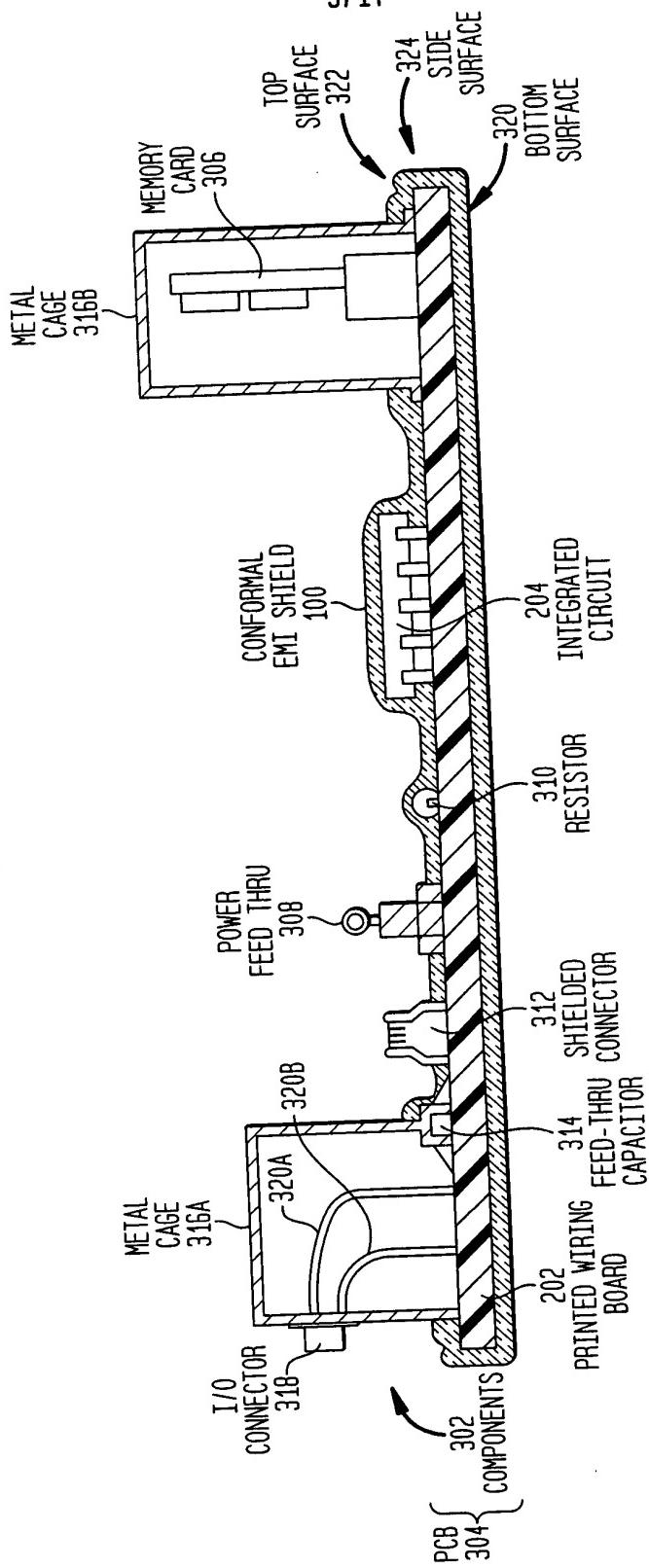
001252 - 000904

FIG. 2C



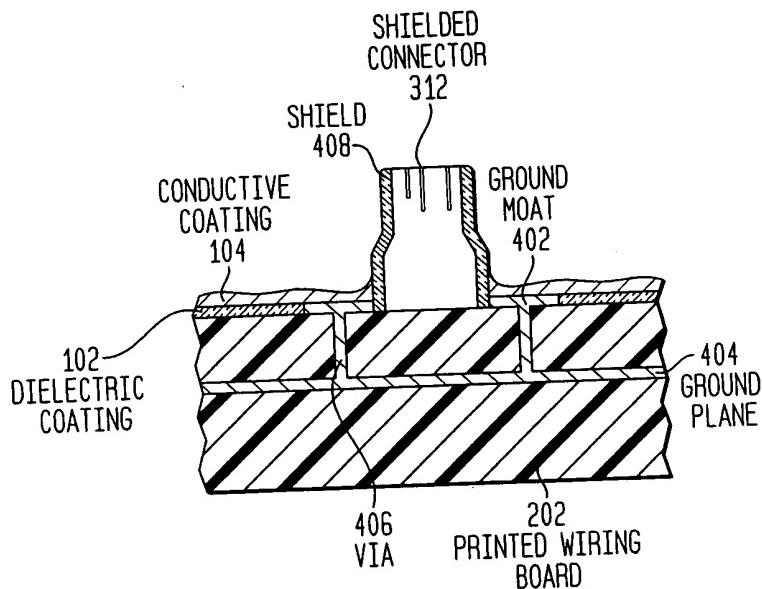
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FIG. 3



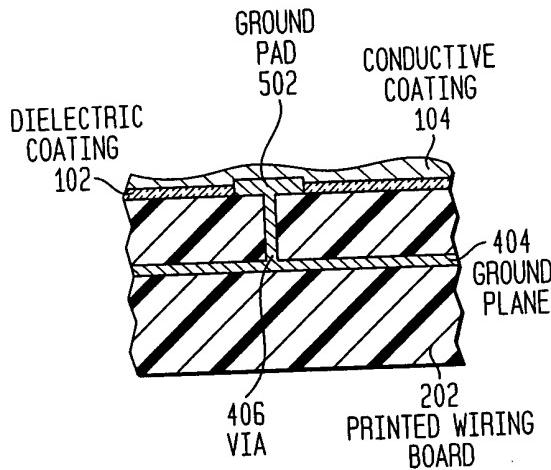
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FIG. 4



P00290 - 2000000000

FIG. 5



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FIG. 6A

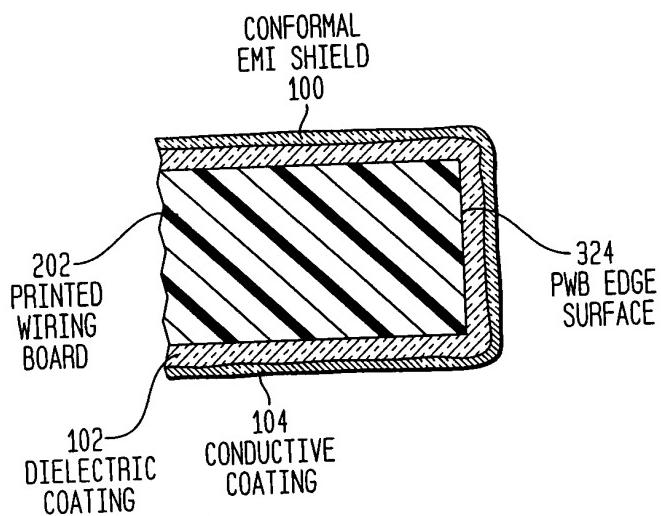
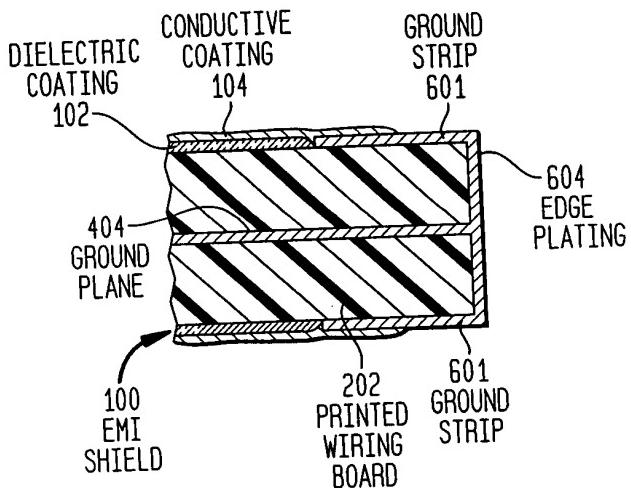


FIG. 6B



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FIG. 6C

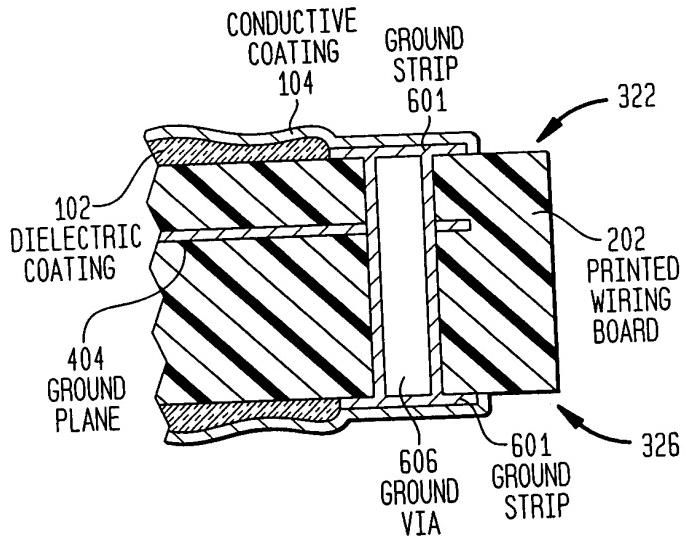
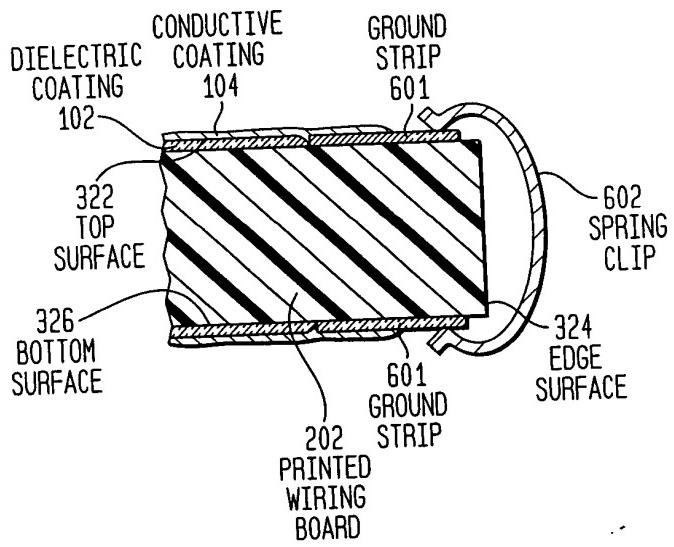


FIG. 6D



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FIG. 6E

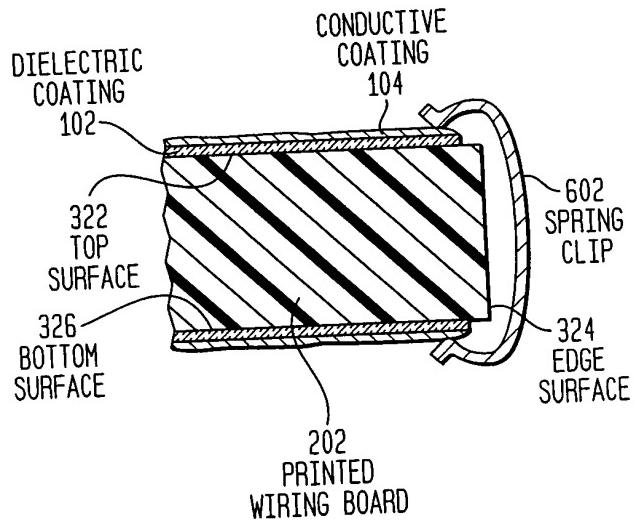
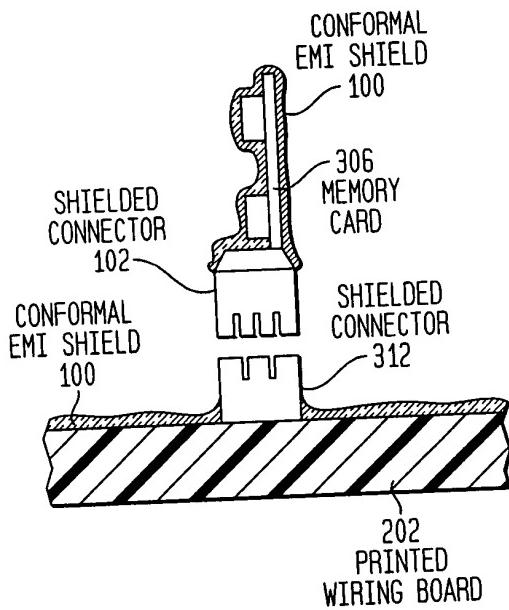


FIG. 7



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FIG. 8A

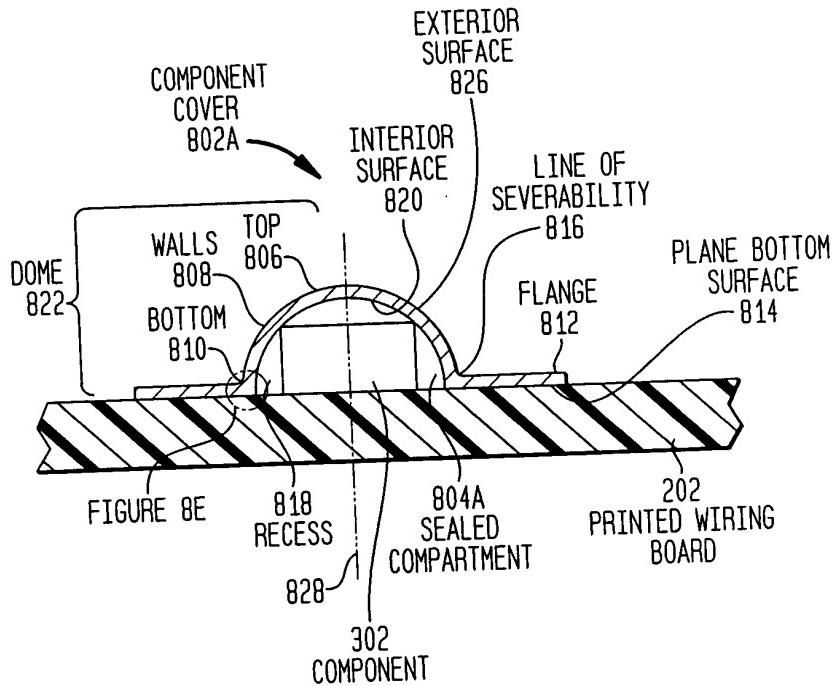
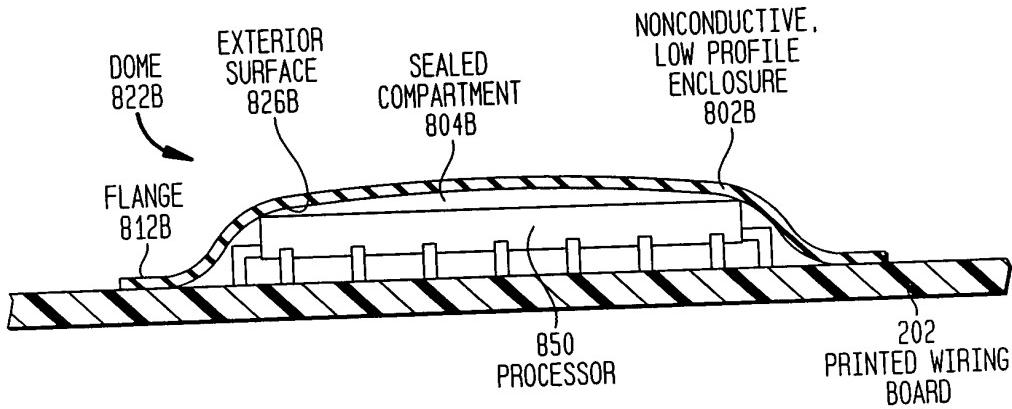


FIG. 8B



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FIG. 8C

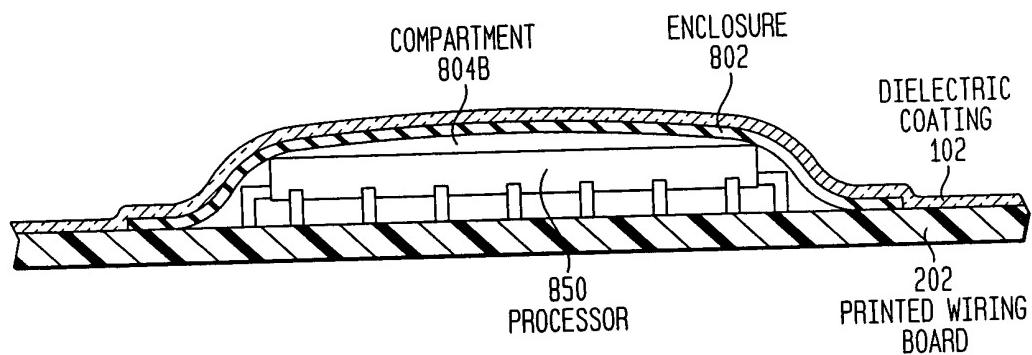
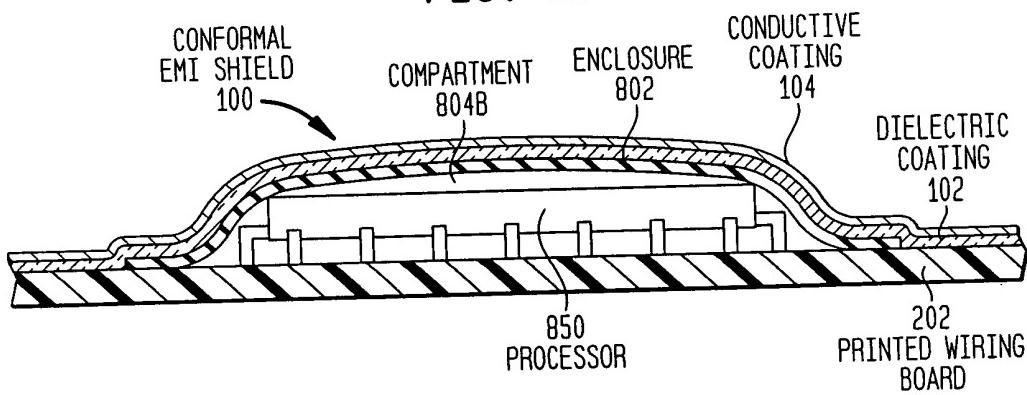


FIG. 8D



Hewlett-Packard 10001844-1
Filler Material And Pretreatment Of Printed
Circuit Board Components To Facilitate
Application Of A Conformal EMI Shield
Inventor(s): Lowell E Kolb et al

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FIG. 8E-1

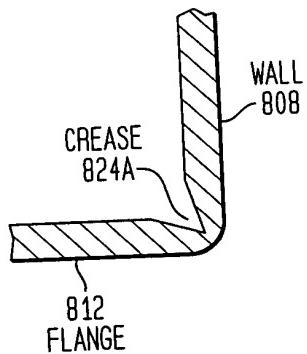
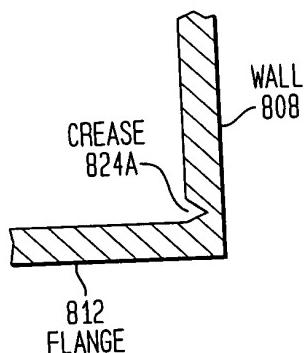


FIG. 8E-2



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FIG. 9A

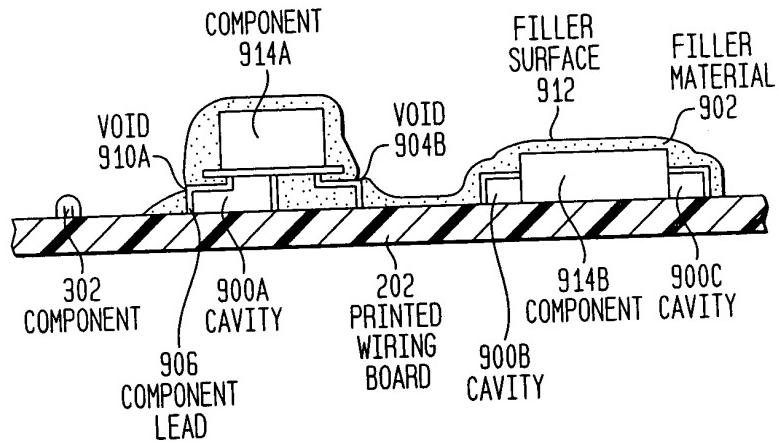
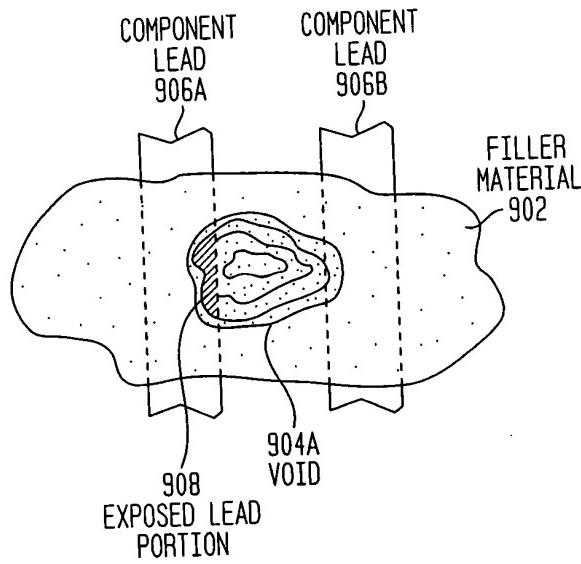


FIG. 9B



Hewlett-Packard 10001844-1

Filler Material And Pretreatment Of Printed
Circuit Board Components To Facilitate
Application Of A Conformal EMI Shield

Inventor(s): Lowell E Kolb et al

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FIG. 9C

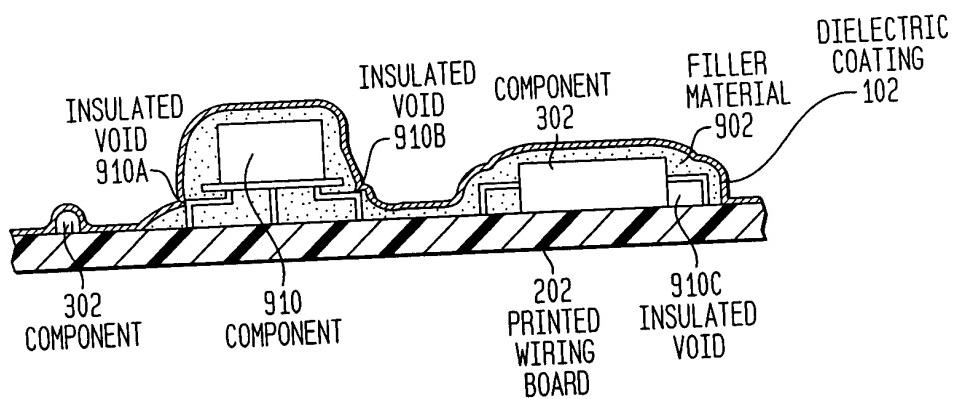


FIG. 9D

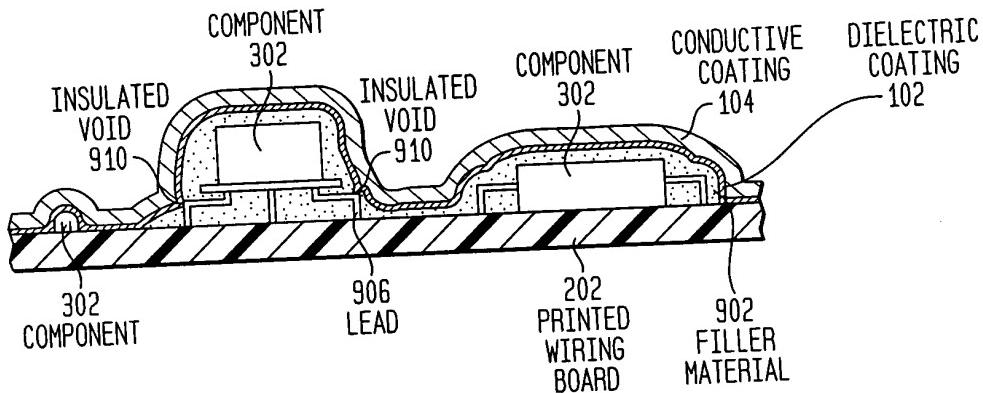


FIG. 10

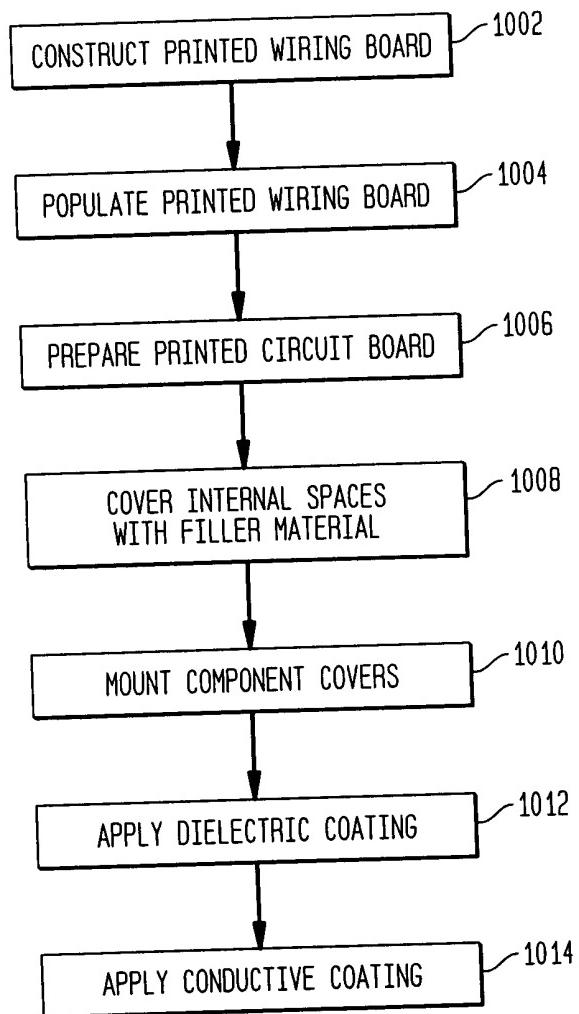


FIG. 11

